

**AMENDMENTS TO THE SPECIFICATION**

Please amend the specification as follows:

Page 3, lines 21-28, please replace the paragraph with the following replacement paragraph:

-- The wafer having bonding pads and the passivation layer is placed into the drilled shipping box 10. After putting the shipping box 10 into the packaging bag 14, the packaging bag 14 is put into the vacuum packaging machine 16. Impurities, such as F (fluorine), are pumped out through an exhaust 18 by the vacuum packaging machine until the pressure is reduced to 350-400 mmHg, as are air and moisture inside the shipping box 10 and between the packaging bag 14 and the shipping box 10. --